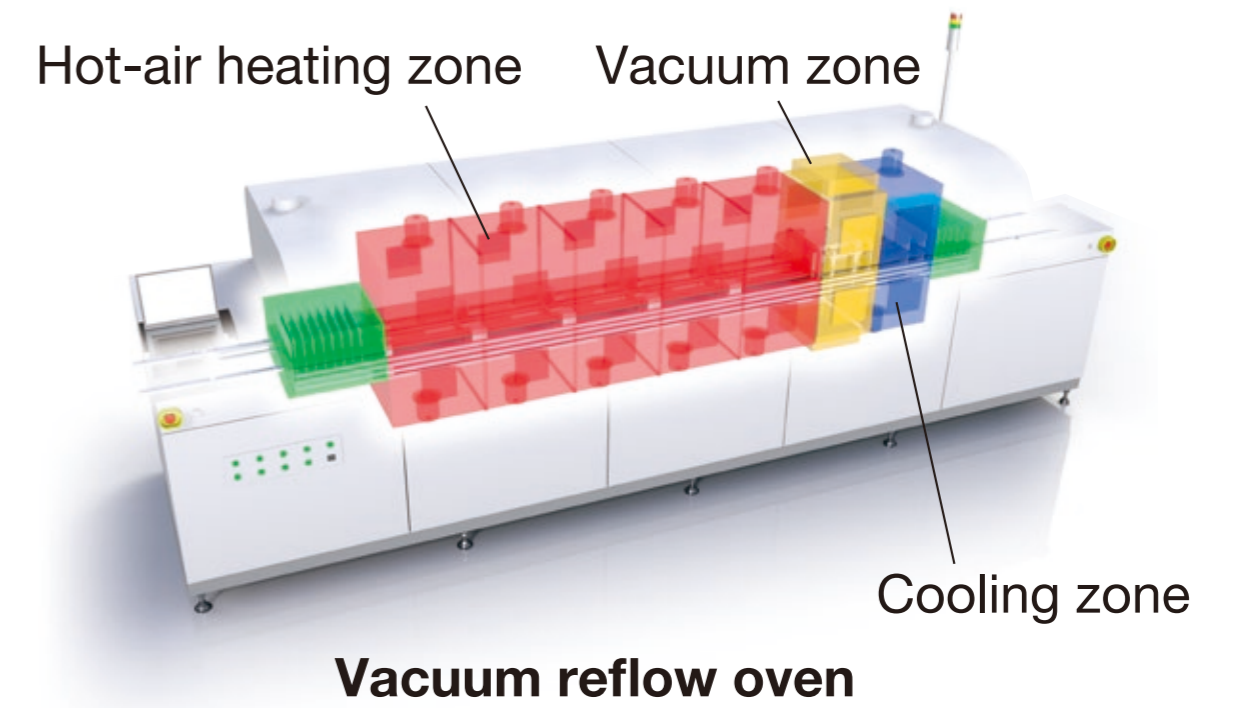


Vacuum Reflow Oven SVR-625GT-C

Vacuum Reflow Oven based on Experienced Soldering Technologies

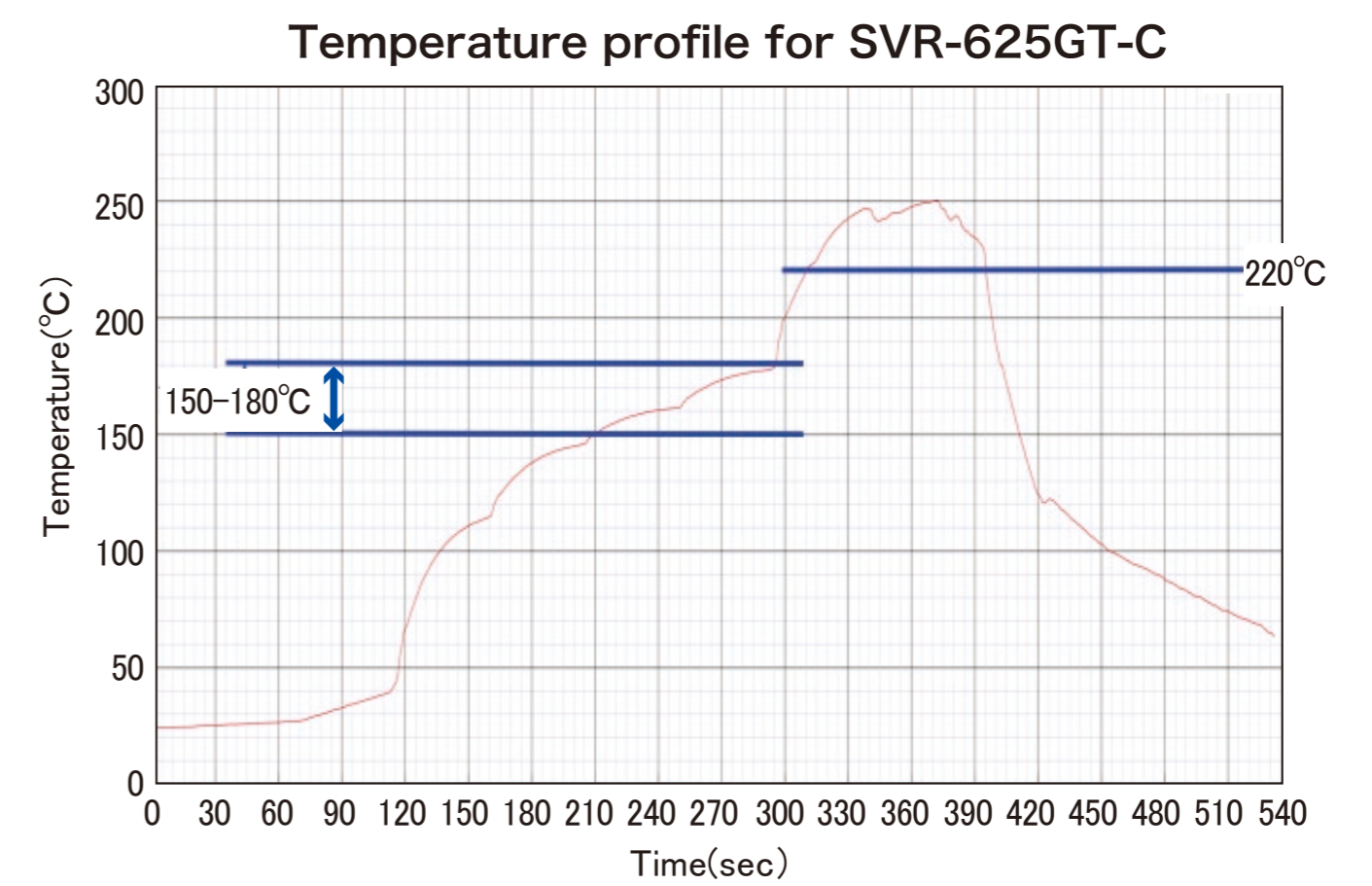
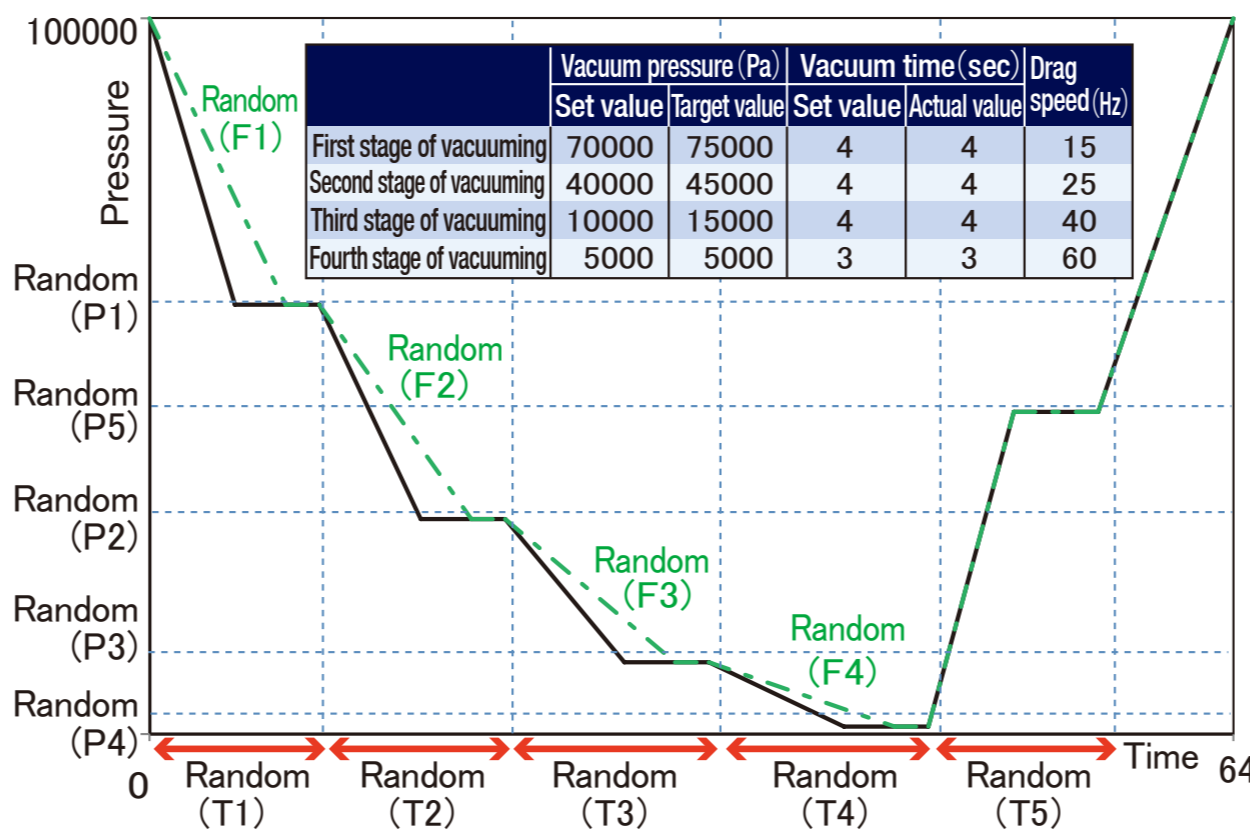
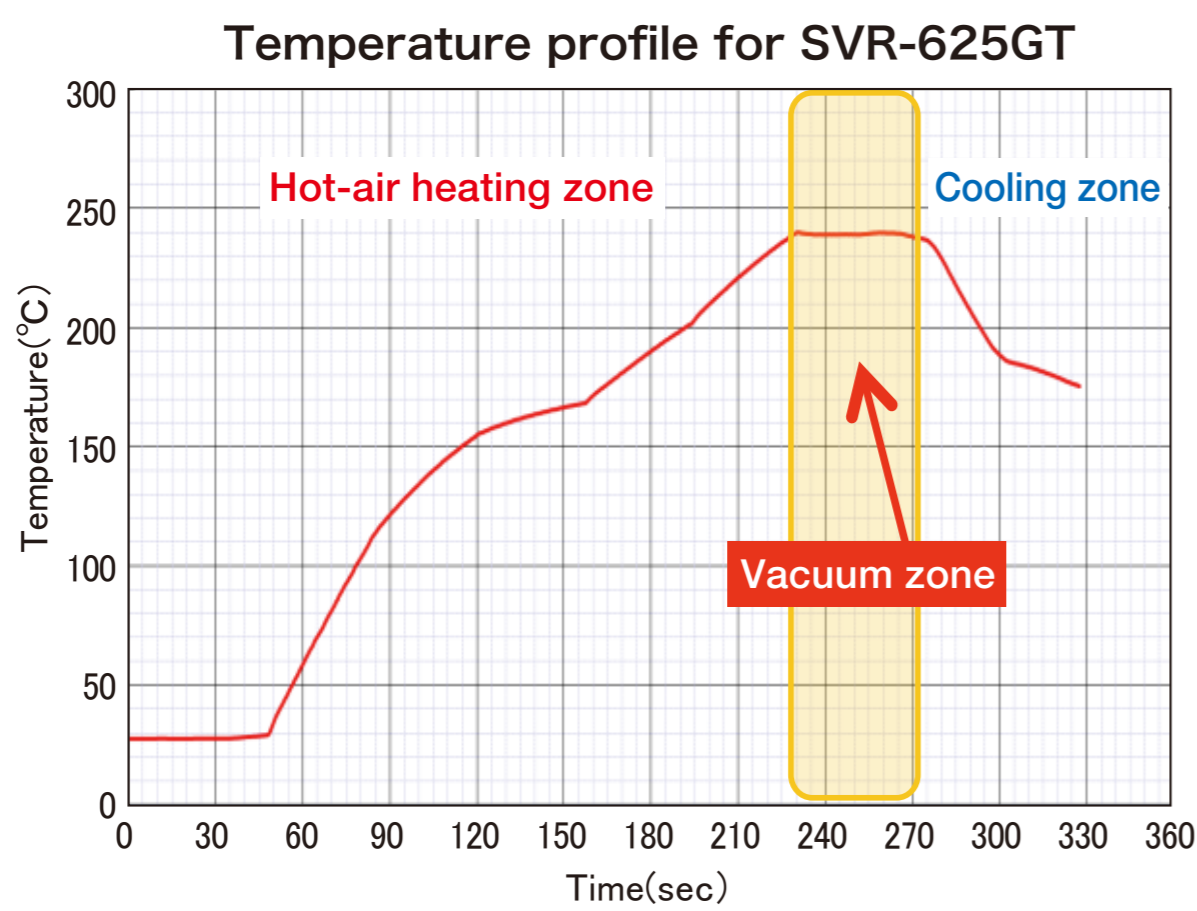
Features

- Decompression at the peak temperature range at which solder melts reduces voids and splashing
- 4 stages of decompression patterns reduce slippage of components and voids in the optimal condition
- A vacuum zone of which temperature is adjustable reduces splashing and voids
- Support high temperature soldering(350°C max.)

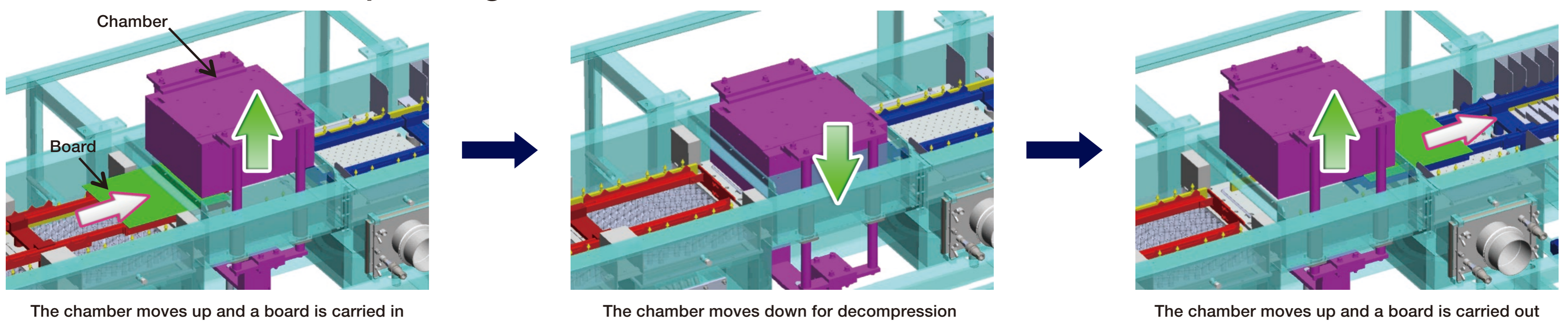


Specifications

- Controls the degree of vacuum and the vacuum time in the optimal condition with solder melting to reduce voids and solder splashing



- An elevating vacuum chamber reproduces a degree of decompression and reduces voids and uneven splashing



- Results of evaluation of void prevention with various components

	QFN 8mm	Pw Tr	LGA 19mm	BGA 19mm
General-purpose oven (Air)				
Vacuum oven (N2) SVR-625GT-C				